



Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

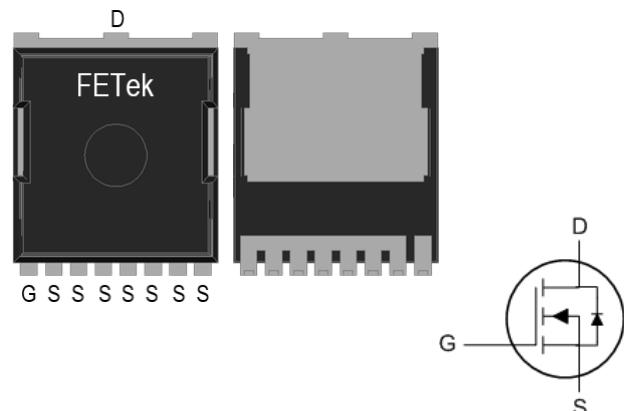
Product Summary

BVDSS	RDS(ON)	ID
100V	1.9mΩ	316A

Applications

- Power Tools.
- Motor Control.
- UPS.
- Synchronous Rectification in SMPS.

TOLL Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current ^{1,6}	316	A
I _D @T _C =100°C	Continuous Drain Current ^{1,6}	224	A
I _{DM}	Pulsed Drain Current ²	1000	A
EAS	Single Pulse Avalanche Energy ³	800	mJ
I _{AS}	Avalanche Current	40	A
P _D @T _C =25°C	Total Power Dissipation ⁴	333	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	40	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.45	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=90\text{A}$	---	1.6	1.9	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	2	---	4	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=100^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=20\text{A}$	---	75	---	S
Q_g	Total Gate Charge	$V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=90\text{A}$	---	212	---	nC
Q_{gs}	Gate-Source Charge		---	59	---	
Q_{gd}	Gate-Drain Charge		---	53	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3\Omega$, $I_D=20\text{A}$	---	47	---	ns
T_r	Rise Time		---	28	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	79	---	
T_f	Fall Time		---	18	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	13362	---	pF
C_{oss}	Output Capacitance		---	1917	---	
C_{rss}	Reverse Transfer Capacitance		---	387	---	

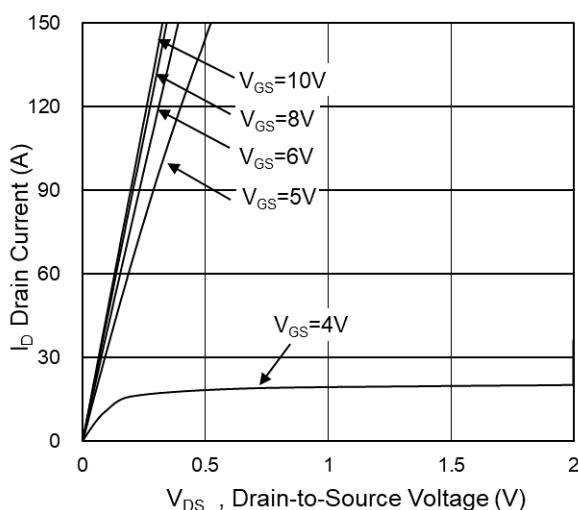
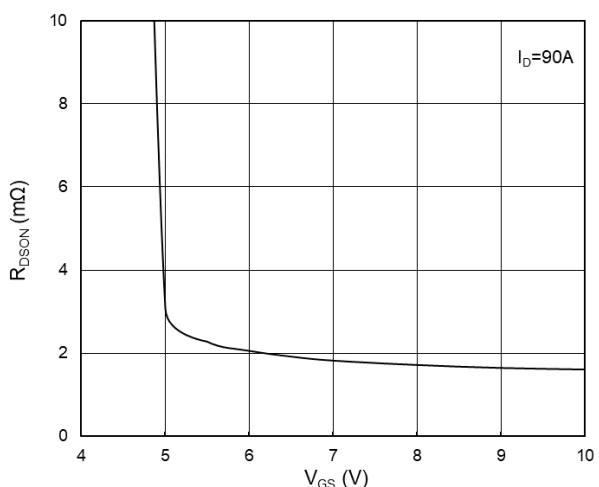
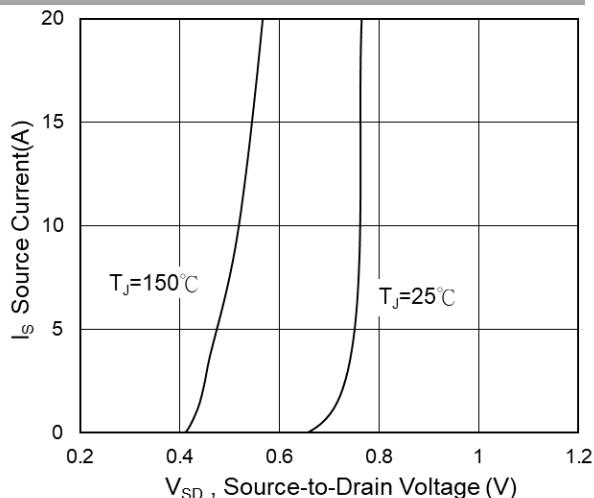
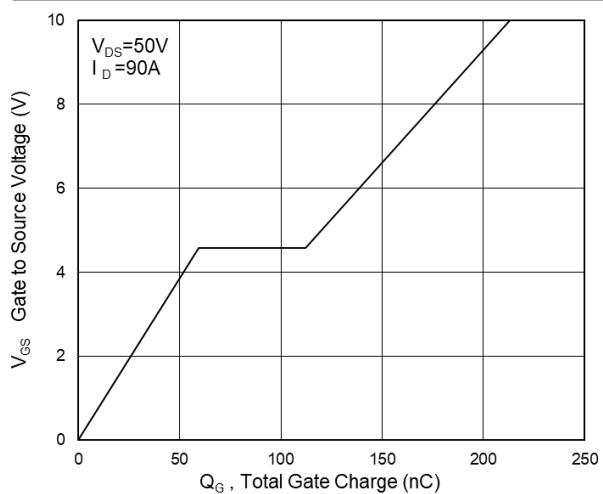
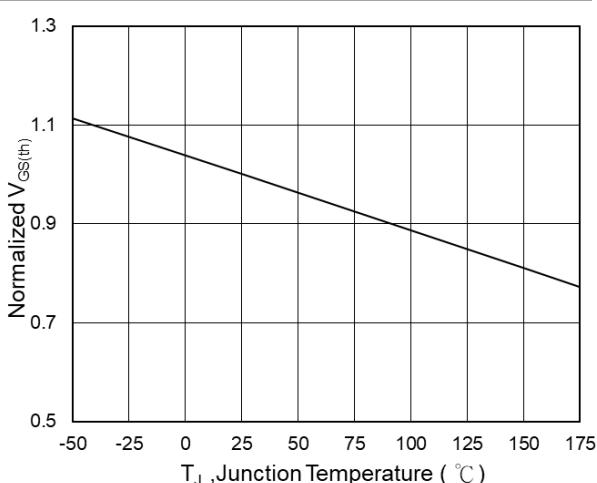
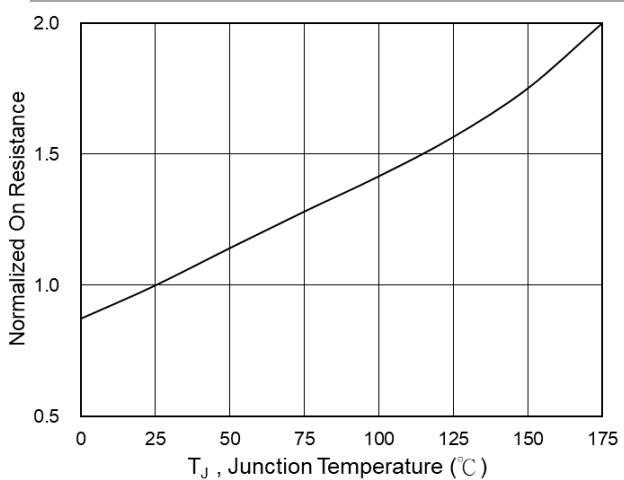
Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5,6}	$V_G=V_D=0\text{V}$, Force Current	---	---	100	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.1	V
t_{rr}	Reverse Recovery Time	$I_F=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$,	---	70	---	nS
		$T_J=25^\circ\text{C}$	---	580	---	nC
Q_{rr}	Reverse Recovery Charge					

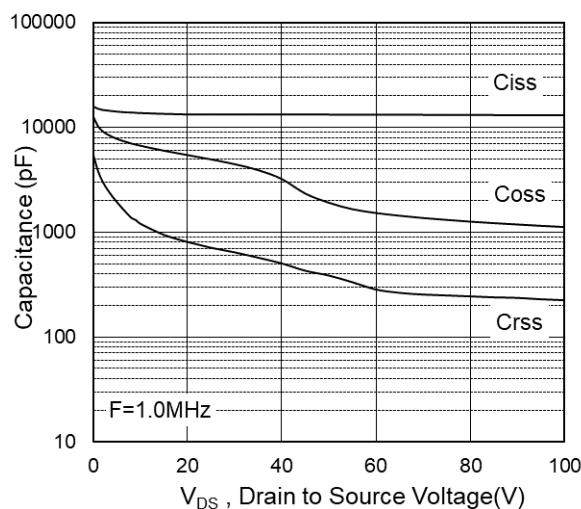
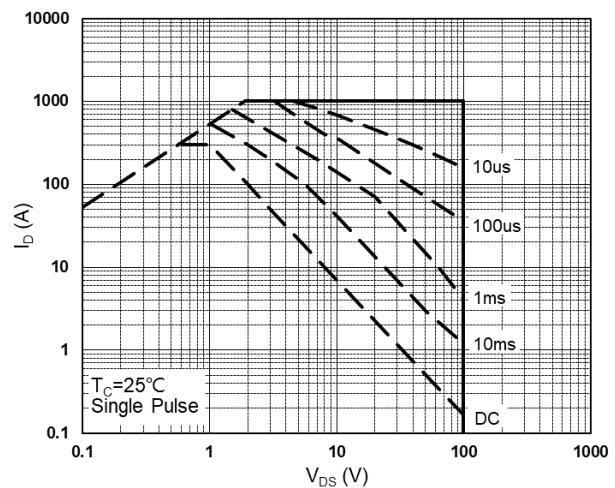
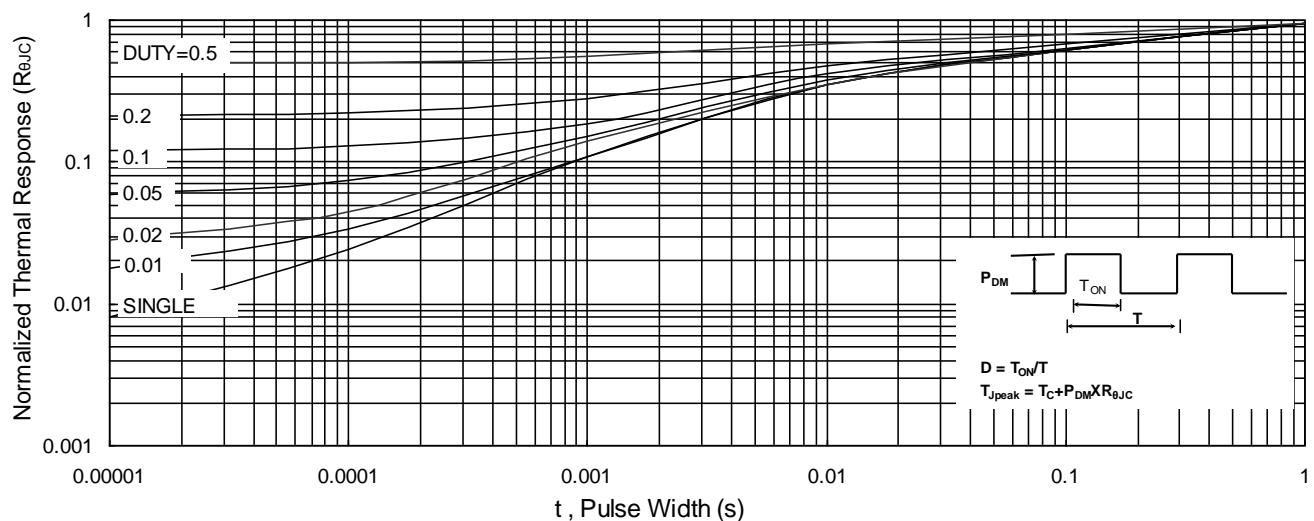
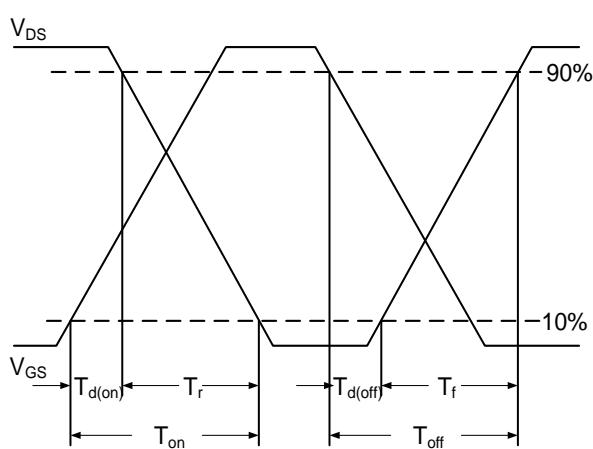
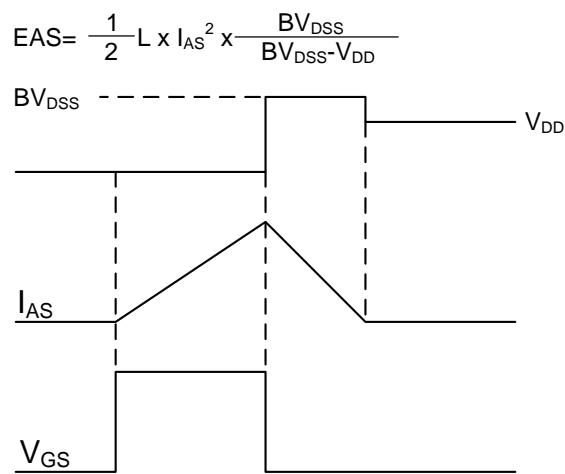
Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=1.0\text{mH}$, $I_{\text{AS}}=40\text{A}$
- 4.The power dissipation is limited by 175°C junction temperature.
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 300A.

Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source-Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs T_J

Fig.6 Normalized $R_{DS(on)}$ vs T_J

Data and specifications subject to change without notice.
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Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform